

# SANYO Semiconductors DATA SHEET

# FTD2008-

N-Channel Silicon MOSFET

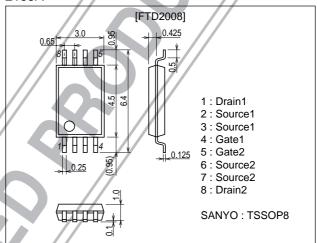
# **DC / DC Converter Applications**

#### **Features**

- · Low ON-resistance.
- · 4V drive.
- Mounting height 1.1mm.
- · Composite type, facilitating high-density mounting.

# **Package Dimensions**

unit : mm 2155A



# **Specifications**

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		60	٧
Gate-to-Source Voltage	VGSS		±20	<b>V</b>
Drain Current (DC)	/ID		1.5	Α
Drain Current (Pulse)	IDP •	PW≤10μs, duty cycle≤1%	6	Α
Allowable Power Dissipation	PD	Mounted on a ceramic board (1000mm <sup>2</sup> X0.8mm) 1unit	0.8	W
Total Dissipation	РТ	Mounted on a ceramic board (1000mm <sup>2</sup> ×0.8mm)	1.0	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

## Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	Offic
Drain-to-Source Breakdown Voltage	V(BR)DSS	I <sub>D</sub> =1mA, V <sub>G</sub> S=0	60			V
Zero-Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =60V, V <sub>GS</sub> =0			10	μΑ
Gate-to-Source Leakage Current	IGSS	VGS=±16V, VDS=0			±10	μΑ
Cutoff Voltage	VGS(off)	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA	1.0		2.4	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> =10V, I <sub>D</sub> =0.8A	1.4	2.0		S

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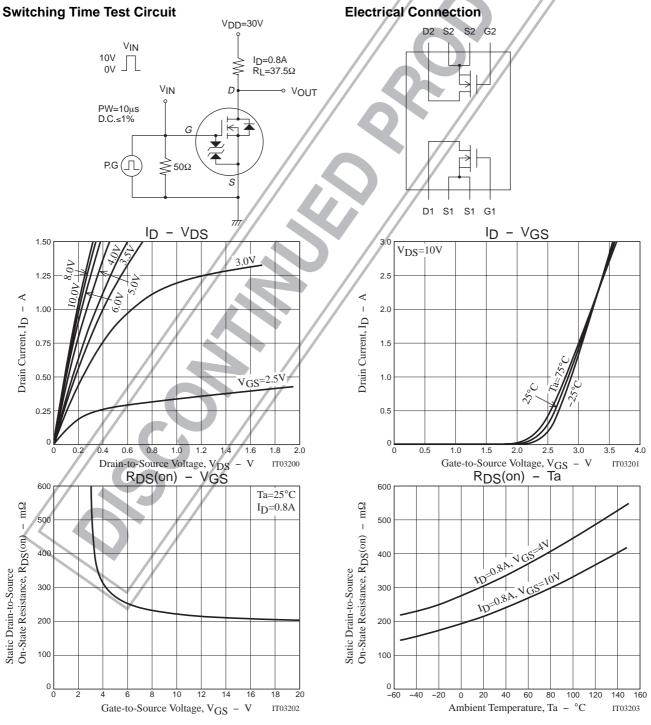
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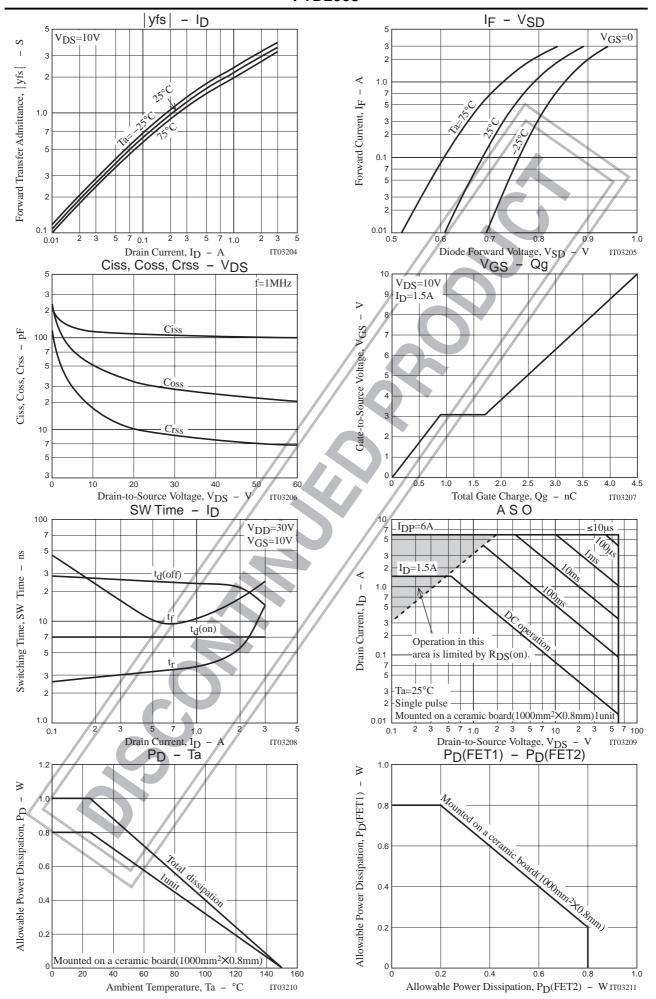
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Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	Uill
Static Drain-to-Source On-State Resistance	R <sub>DS</sub> (on)1	I <sub>D</sub> =0.8A, V <sub>GS</sub> =10V		240	320	mΩ
	R <sub>DS</sub> (on)2	I <sub>D</sub> =0.8A, V <sub>G</sub> S=4V		320	440	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> =20V, f=1MHz		110		pF
Output Capacitance	Coss	V <sub>DS</sub> =20V, f=1MHz		35		pF
Reverse Transfer Capacitance	Crss	V <sub>DS</sub> =20V, f=1MHz		10		pF
Turn-ON Delay Time	t <sub>d</sub> (on)	See specified Test Circuit		7		ns
Rise Time	t <sub>r</sub>	See specified Test Circuit		4		ns
Turn-OFF Delay Time	t <sub>d</sub> (off)	See specified Test Circuit		24		ns
Fall Time	tf	See specified Test Circuit		11		ns
Total Gate Charge	Qg	V <sub>DS</sub> =10V, V <sub>GS</sub> =10V, I <sub>D</sub> =1.5A		4.5		nC
Gate-to-Source Charge	Qgs	V <sub>DS</sub> =10V, V <sub>GS</sub> =10V, I <sub>D</sub> =1.5A		0.9		nC
Gate-to-Drain "Miller" Charge	Qgd	V <sub>DS</sub> =10V, V <sub>GS</sub> =10V, I <sub>D</sub> =1.5A		0.8		nC
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =1.5A, V <sub>GS</sub> =0		0.82	1.2	V







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